

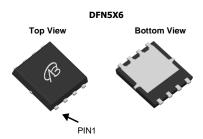
BSC026N08NS5ATMA1-VB Datasheet N-Channel 85V (D-S) MOSFET

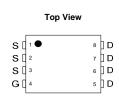
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a		
85	0.003at V _{GS} = 10 V	140		
	0.004at V _{GS} = 4.5 V	130		

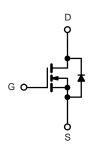
FEATURES

- 175 °C Junction Temperature
- SGT technology Power MOSFET
- Material categorization:









N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Gate-Source Voltage	V _{GS}	±20	V			
Continuous Dunin Comment (T., 475 9C)D	T _C = 25 °C	,	140			
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 100 °C	l l _D	85 ^a]		
Pulsed Drain Current	I _{DM}	420	А			
Continuous Source Current (Diode Conduction)	I _S	80 ^a				
Avalanche Current		I _{AS}	70			
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E _{AS}	133	mJ		
Maximum Power Dissipation	T _C = 25 °C	P _D	136	W		
iviaximum rower bissipation	T _A = 25 °C] 'D	3 ^b , 8.3 ^{b, c}	VV		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Marian and Irration to Ambianta	t ≤ 10 sec	R _{thJA}	15	18	°C/W	
Maximum Junction-to-Ambient ^a	Steady State		40	50		
Maximum Junction-to-Case		R _{thJC}	0.85	1.1		

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. $t \le 10$ s.



Parameter	Symbol	Test Conditions		Typ. ^a	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	85			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1	2	3	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
		V _{DS} = 30V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ
		V _{DS} = 30V, V _{GS} = 0 V, T _J = 175 °C			250	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	60			Α
		V _{GS} = 10 V, I _D = 20 A		0.003		
D : 0	D	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.008		0
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 175 °C		0.010		Ω
		V _{GS} = 4.5 V, I _D = 46 A		0.004		
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		60		S
Dynamic			•	•		
Input Capacitance	C _{iss}			8600		
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 85 \text{ V}, f = 1 \text{ MHz}$		470		pF
Reverse Transfer Capacitance	C _{rss}			225		
Total Gate Charge ^c	Qg			92	70	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 85 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		16		nC
Gate-Drain Charge ^c	Q _{gd}			19		
Turn-On Delay Time ^c	t _{d(on)}			20	21	
Rise Time ^c	t _r	V_{DD} = 85 V, R_L = 0.6 Ω		15	25	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		35	50	- ns
Fall Time ^c	t _f			20	30	
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)				
Pulsed Current	I _{SM}				420	Α
Diode Forward Voltage	V_{SD}	I _F = 20 A, V _{GS} = 0 V		1	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		4	135	ns

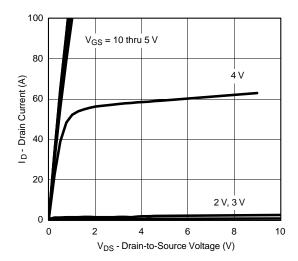
Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. Independent of operating temperature.

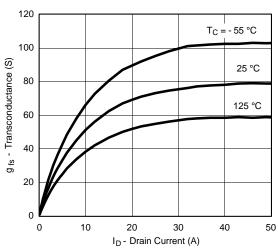
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



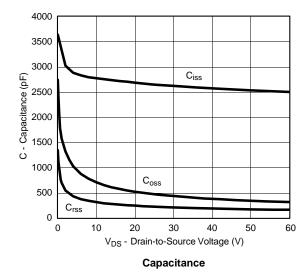
TYPICAL CHARACTERISTICS (25 °C unless noted)



Output Characteristics



Transconductance

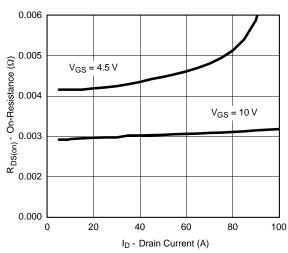


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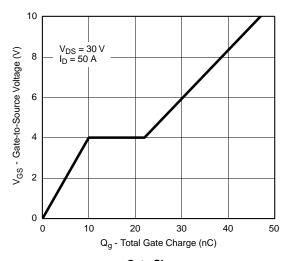
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Transfer Characteristics



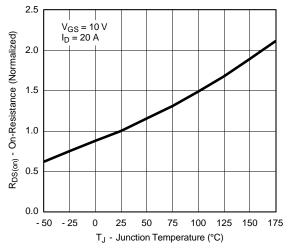
On-Resistance vs. Drain Current



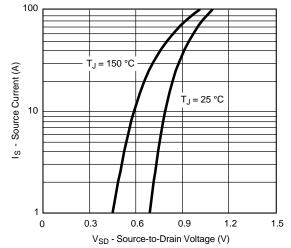
Gate Charge



TYPICAL CHARACTERISTICS (25 °C unless noted)



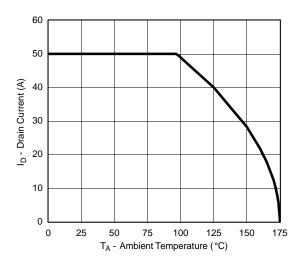
On-Resistance vs. Junction Temperature

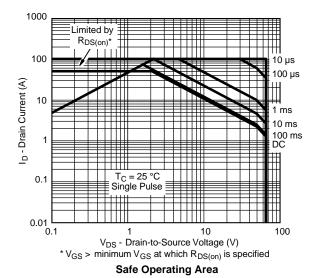


Source-Drain Diode Forward Voltage

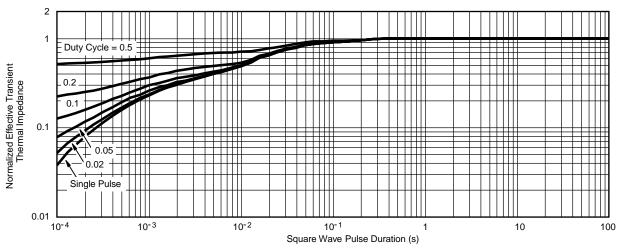


THERMAL RATINGS





Maximum Drain Current vs. Ambient Temperature



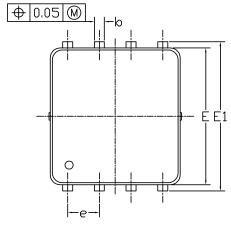
Normalized Thermal Transient Impedance, Junction-to-Case

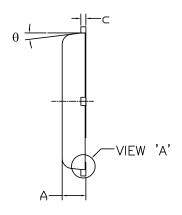
服务热线:400-655-8788

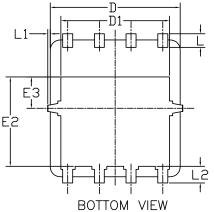
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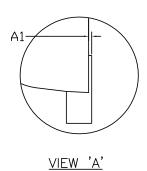


DFN5x6_8L_EP1_P PACKAGE OUTLIN



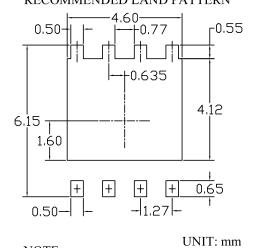






(SCALE 5:1)

RECOMMENDED LAND PATTERN



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
SIMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
A	0.85	0. 95	1.00	0.033	0.037	0.039
A1	0.00		0.05	0.000		0.002
b	0.30	0.40	0.50	0.012	0.016	0.020
c	0. 15	0. 20	0. 25	0.006	0.008	0.010
D	5. 10	5. 20	5. 30	0. 201	0. 205	0. 209
D1	4. 25	4. 35	4. 45	0. 167	0.171	0. 175
Е	5. 45	5. 55	5. 65	0. 215	0.219	0. 222
E1	5. 95	6.05	6. 15	0. 234	0. 238	0. 242
E2	3. 525	3.625	3. 725	0. 139	0. 143	0. 147
E3	1. 175	1. 275	1. 375	0.046	0.050	0.054
e	1. 27 BSC				0.050 BSC	
L	0.45	0. 55	0.65	0.018	0.022	0.026
L1	0		0. 15	0		0.006
L2	0.68 REF			0.027 REF		
θ	0°		10°	0°		10°

NOTE

- 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
 MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
- 2. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.



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